

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Currently Amended): A semiconductor laser module comprising:

a semiconductor laser element configured to produce laser light; [[and]]

a package ~~being~~ hermetically sealed and having an interior space that contains the semiconductor laser element, ~~said package including a first side allowing said laser light to pass therethrough, and a second side positioned across said interior space from said first side;~~

a vent member disposed in said second side ~~that extends and extending~~ from said interior space to a space that is exterior to said package, said vent member configured to transport the low heat conduction gas from a gas source to the interior space when unsealed, and said vent member configured to prevent a flow of gas between the interior space and the exterior when sealed

~~wherein, when unsealed, said vent member being configured to transport a low heat conduction gas between the interior space and the exterior, and when sealed, said vent member being configured to prevent a flow of gas between the interior space and the exterior.~~

Claim 2 (Canceled).

Claim 3 (Currently Amended): The semiconductor laser module according to claim 1, wherein:

said vent member ~~being~~ is shaped as a pipe.

Claim 4 (Currently Amended): The semiconductor laser module according to claim 1, wherein:

said vent member is ~~configured to be~~ hermetically sealed after an occurrence of at least one of a first condition and a second condition,

said first condition being that the low heat conductor gas has been introduced into the package via the vent member, and

said second condition being that the low heat conduction gas has been exhausted from the package via the vent member.

Claim 5 (Currently Amended): The semiconductor laser module of claim 4, wherein:

~~said package having a first side and a second side, said second side being positioned across said interior space from said first side;~~

~~said first side being configured to allow said laser light to pass therethrough, and said vent member being disposed in said second side; and~~

the vent member contains a portion that extends beyond the second side of said package, and the portion of said vent member is sealed first by being swaged and subsequently by being welded.

Claim 6 (Original): The semiconductor laser module of claim 4, wherein:

said vent member is configured to receive the low heat conduction gas from a gas introducing device when said vent member is not sealed.

Claim 7 (Original): The semiconductor laser module of claim 6, wherein:

said vent member is configured to receive the low heat conduction gas from the gas introducing device via a controllable valve.

Claim 8 (Original): The semiconductor laser module of claim 6, wherein:

said selector device is configured to select one of

the low heat conduction gas from the gas introducing device to be provided to the package, and

gas contained in the interior space of the package to be exhausted from the interior space.

Claim 9 (Currently Amended): The semiconductor laser module of claim 1, further comprising:

another vent member that extends from said interior space to outside of said package, wherein

~~said vent member when unsealed is configured to receive a low heat conduction gas from a gas source, and~~

said another vent member ~~when unsealed~~ is configured to exhaust gas from said interior space when unsealed.

Claim 10 (Original): The semiconductor laser module of claim 1, wherein:

said vent member is configured to be sealed by being swaged closed.

Claim 11 (Original): The semiconductor laser module of claim 10, wherein:

said vent member is configured to be permanently sealed by being welded shut after being swaged.

Claim 12 (Currently Amended): A semiconductor laser module comprising:

a semiconductor laser element configured to produce laser light; [[and]]

a package ~~being~~ hermetically sealed and having an interior space that contains the semiconductor laser element, ~~said package includes~~ a first side allowing said laser light to pass therethrough, and a second side positioned across said interior space from said first side;

means for providing a low heat conduction gas to the interior space, said means for providing a low heat conduction gas being disposed in said second side; and

means for exhausting gas from the interior space, said means for exhausting gas being disposed in said second side.

Claims 13-19 (Cancelled).